

METHODS, SYSTEMS AND COMPUTER PROGRAM PRODUCTS FOR
DYNAMICALLY CONTROLLING A SEMICONDUCTOR DICING SAW

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Abstract of the Disclosure

A saw cutting pattern is dynamically established for a semiconductor dicing saw based on detection of the saw blade contacting a wafer or a portion of a wafer. The dynamic cutting pattern may terminate cuts if the saw blade no longer contacts the wafer or a portion of a wafer. Thus, irregular shaped wafers may be cut without requiring that an entire predefined cutting pattern be carried out and/or without previously mapping the shape of the wafer or portion of a wafer. A map of the wafer or a portion of a wafer may also be generated based on the detection of the saw blade contacting the wafer during a first cutting pass and may be used during a second cutting pass.

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